

Test Report: PMP23278

# Class 4 PoE PD Active Clamp Forward Converter (12 V, 2.1 A) Reference Design



## Description

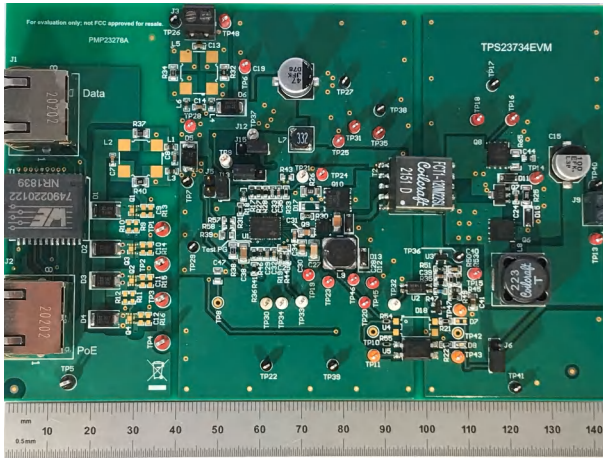
This reference design implements a Power over Ethernet (PoE) Power Device (PD) Active Clamp Forward converter with a 12-V, 2.1-A output. A TPS23734 PD, pulse-width modulation (PWM) controller provides all the necessary functions to implement the PoE PD control and the PWM control for the Active Clamp Forward converter. This design uses secondary-side regulation (SSR), with an optocoupler feedback.

## Feature

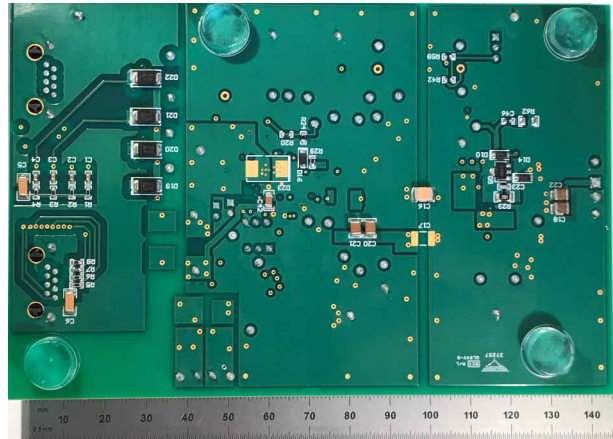
- Combined PD and PWM controller
- Secondary-side regulation (using optocoupler)
- Optional 48-V adapter input
- Frequency dithering for improved EMI

## Applications

- [IP network camera](#)
- [WLAN, Wi-Fi® access point](#)
- [Barcode reader](#)



Top Photo



Bottom Photo

## 1 Test Prerequisites

### 1.1 Voltage and Current Requirements

**Table 1-1. Voltage and Current Requirements**

Parameter	Specifications
Input voltage	37 V–57 V (48 V nominal)
Output voltage	12 V
Output current	2.1 A
Nominal Switching Frequency	250 kHz

### 1.2 Required Equipment

- Type 2 PoE Power Source Equipment (PSE)
- Isolated DC power source, 0 V–57 V, 1-A minimum
- 12-V, 5-A electronic load

### 1.3 Considerations

- All measurements were taken at approximately 25°C ambient
- All measurements taken with 48-V input and 2.1-A load, unless noted

## 2 Testing and Results

### 2.1 Efficiency Graphs

Figure 2-1 shows the PMP23278 efficiency curve.

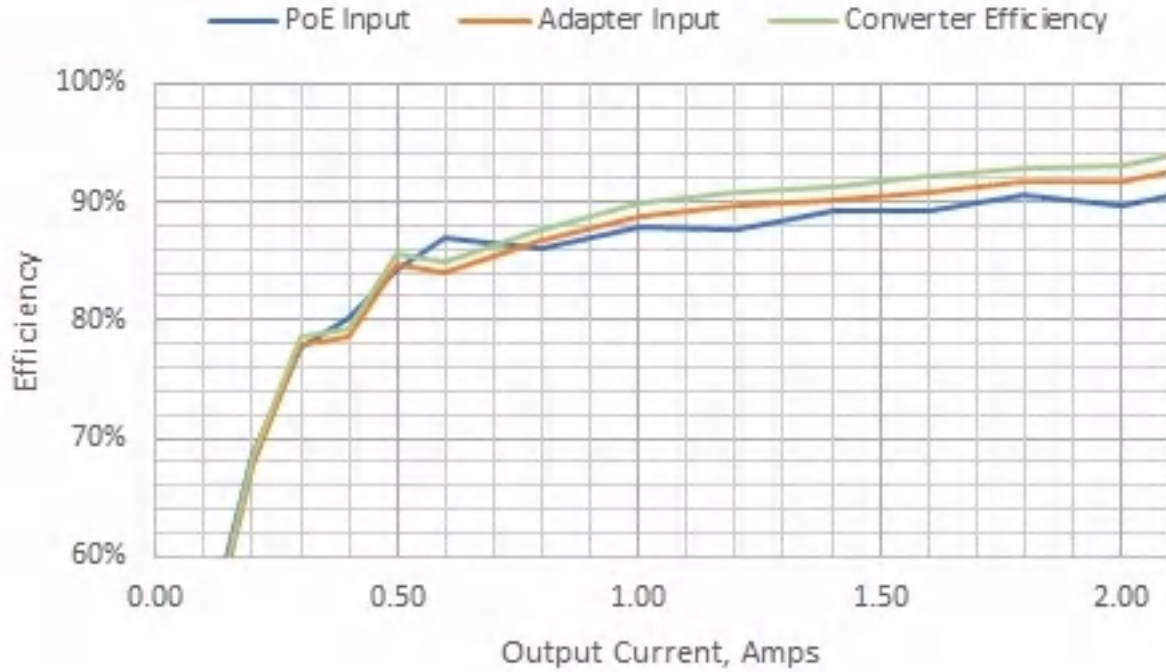


Figure 2-1. PMP23278 Rev. B Efficiency Graph, PoE Diode Bridge

## 2.2 Efficiency Data

Efficiency data is shown in the following tables.

$I_{OUT}$ (J9)	$V_{OUT}$ (J9)	$I_{IN}$ (J2)	$V_{IN}$ (J2)	Eff (J2)
0.00	12.08	0.025	48.00	0.0%
0.10	12.08	0.048	48.00	52.5%
0.20	12.08	0.073	48.00	68.6%
0.30	12.08	0.097	48.00	77.7%
0.40	12.08	0.126	48.01	80.2%
0.50	12.08	0.1499	48.00	84.2%
0.60	12.08	0.174	48.01	87.0%
0.80	12.08	0.234	48.02	86.0%
1.00	12.08	0.287	48.01	87.8%
1.20	12.08	0.344	48.00	87.7%
1.40	12.08	0.395	48.01	89.1%
1.60	12.08	0.451	48.00	89.3%
1.80	12.08	0.501	48.00	90.5%
2.00	12.08	0.561	48.01	89.7%
2.08	12.08	0.579	48.01	90.4%
2.20	12.08	0.606	48.01	91.4%

$I_{OUT}$ (J9)	$V_{OUT}$ (J9)	$I_{IN}$ (J3)	$V_{IN}$ (J3)	Eff (J3)	$V_{IN}$ (VDD,PGND)	Eff (CONV)
0.00	12.08	0.0253	48.00	0.0%	47.60	0.0%
0.10	12.08	0.049	48.00	51.0%	47.57	51.5%
0.20	12.08	0.074	48.00	67.8%	47.54	68.5%
0.30	12.08	0.097	48.00	77.8%	47.54	78.6%
0.40	12.08	0.128	48.01	78.5%	47.52	79.3%
0.50	12.08	0.149	48.00	84.6%	47.50	85.5%
0.60	12.08	0.180	48.00	84.0%	47.48	84.9%
0.80	12.08	0.232	48.00	86.7%	47.45	87.7%
1.00	12.08	0.284	48.00	88.7%	47.43	89.8%
1.20	12.08	0.337	48.00	89.6%	47.40	90.8%
1.40	12.08	0.391	48.00	90.1%	47.37	91.3%
1.60	12.08	0.443	48.00	90.8%	47.35	92.1%
1.80	12.08	0.494	48.00	91.6%	47.33	92.9%
2.00	12.08	0.549	48.00	91.8%	47.31	93.1%
2.11	12.08	0.574	48.00	92.6%	47.30	93.9%
2.20	12.08	0.602	48.00	92.0%	47.29	93.4%

### 2.3 Thermal Images

Figure 2-2 and Figure 2-3 show the thermal images at full load and nominal line (48 V).

#### Measurements

Sp1	38.6 °C
Sp2	31.2 °C
Sp3	35.4 °C
Sp4	30.6 °C
Sp5	30.4 °C
Sp6	39.8 °C
Sp7	30.7 °C
Sp8	32.2 °C
Sp9	38.3 °C

#### Parameters

Emissivity	0.94
Refl. temp.	20 °C

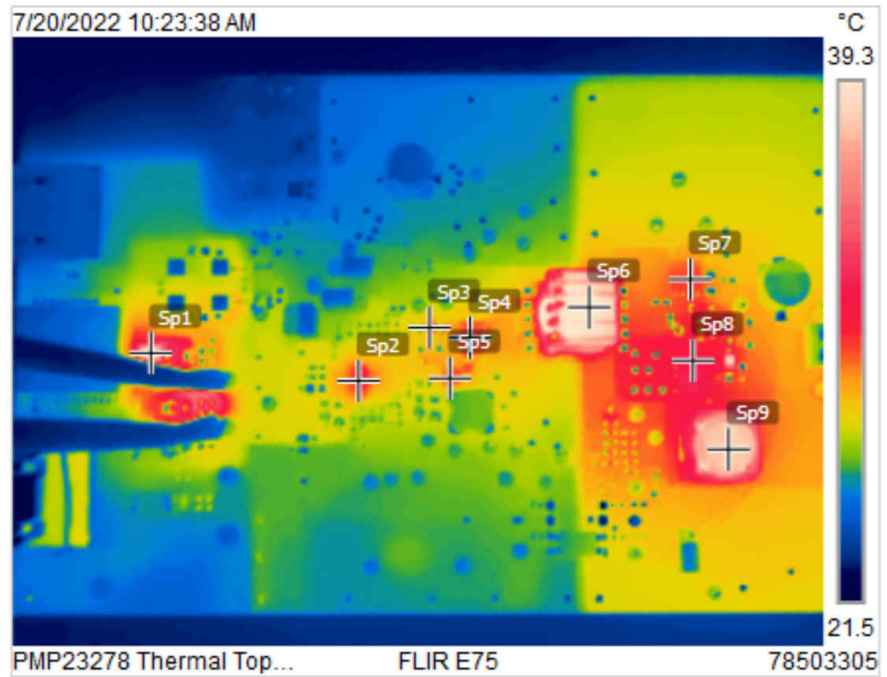


Figure 2-2. Top Thermal Image

#### Measurements

Sp1	44.3 °C
Sp2	33.5 °C
Sp3	37.3 °C

#### Parameters

Emissivity	0.94
Refl. temp.	20 °C

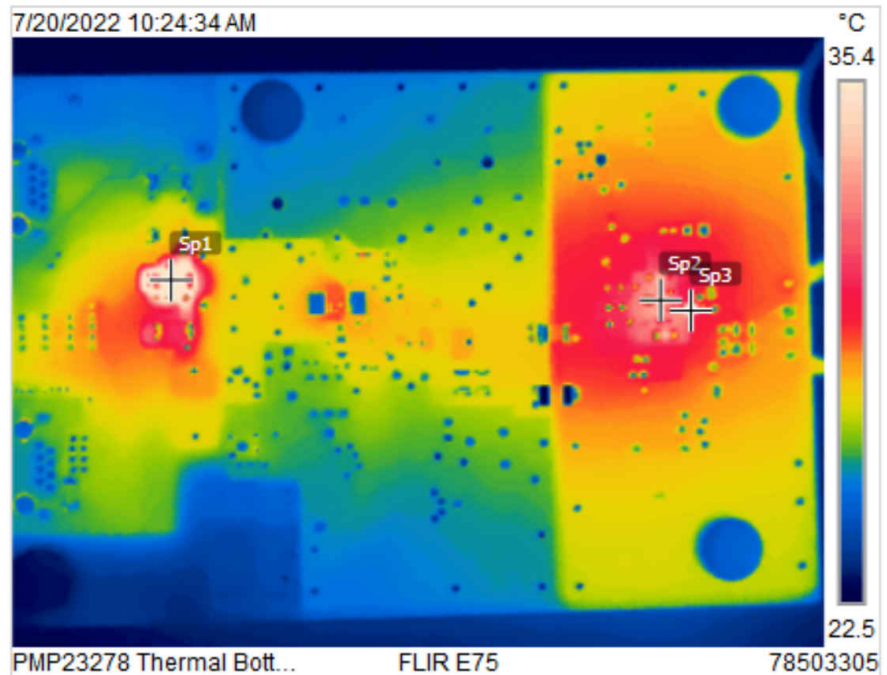
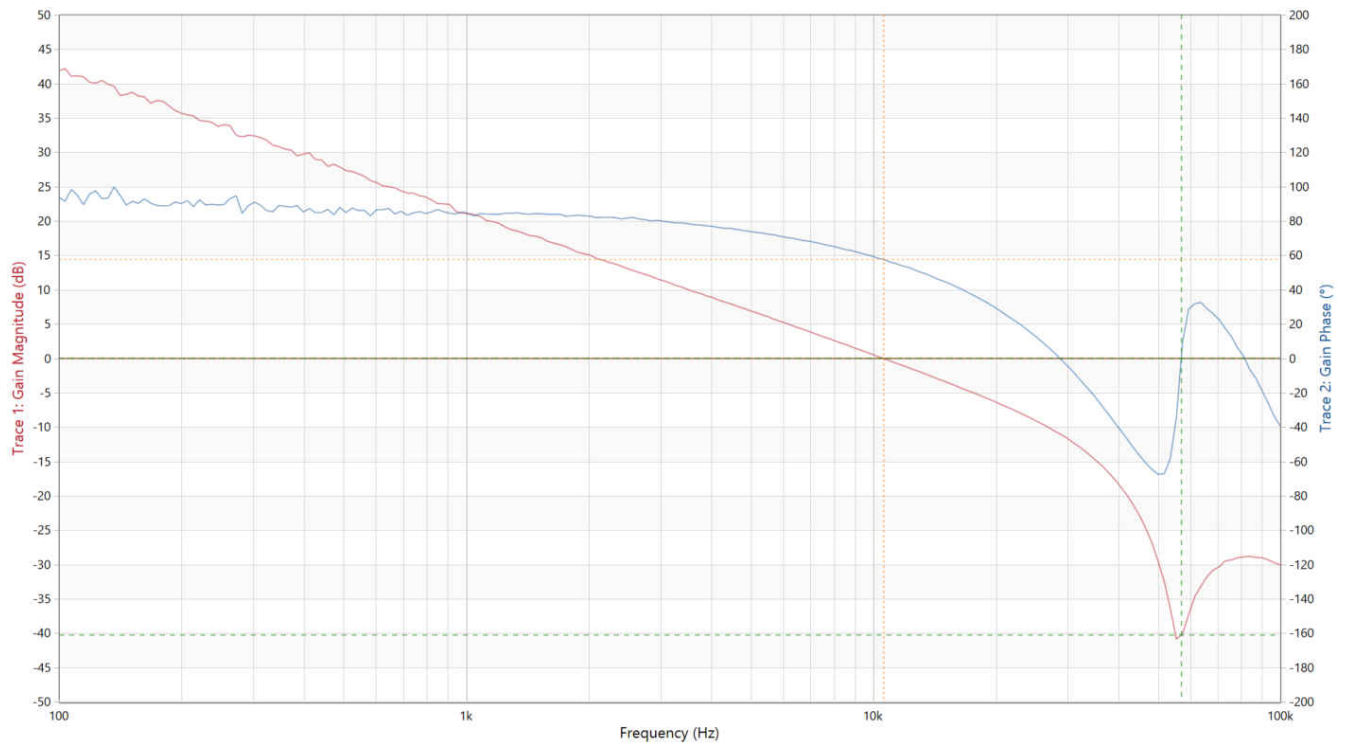


Figure 2-3. Bottom Thermal Image

## 2.4 Bode Plots

Figure 2-4 shows the bode plot waveform.

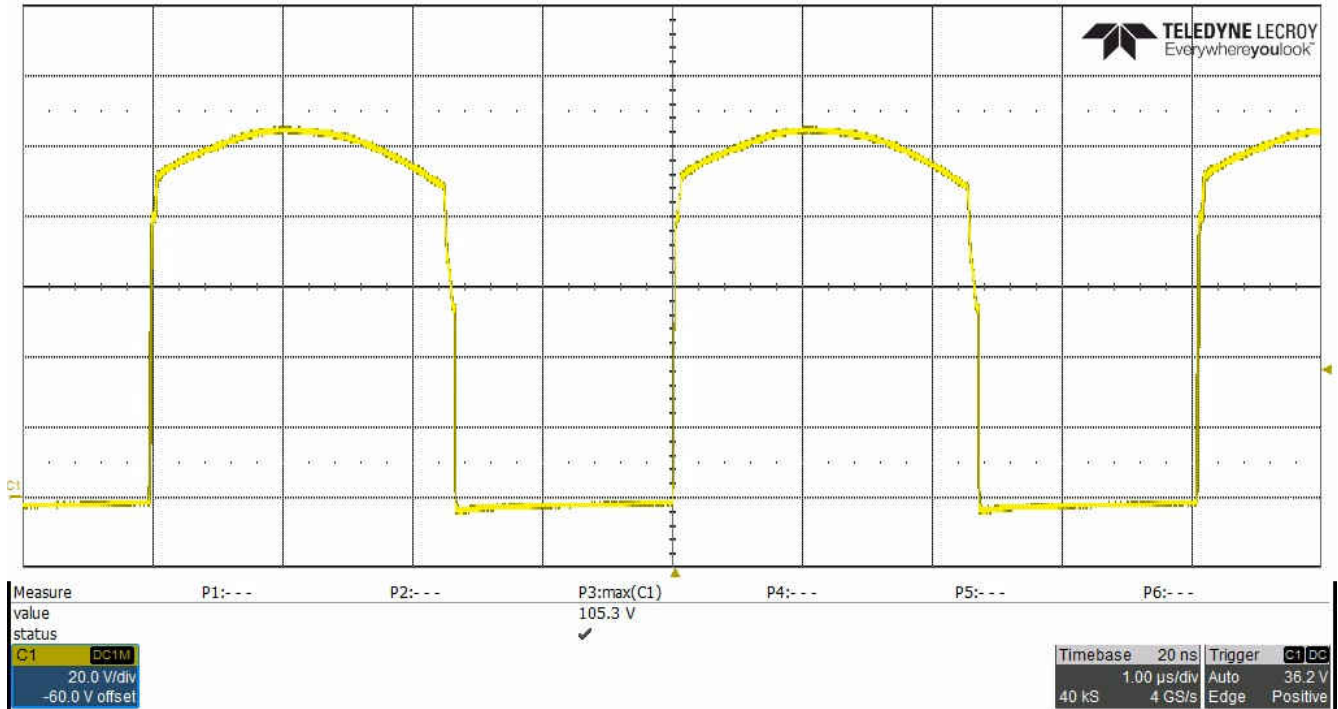


**Figure 2-4. Bandwidth = 10.6 kHz, Phase Margin = 57.6 degrees, Gain Margin = 40.3 dB**

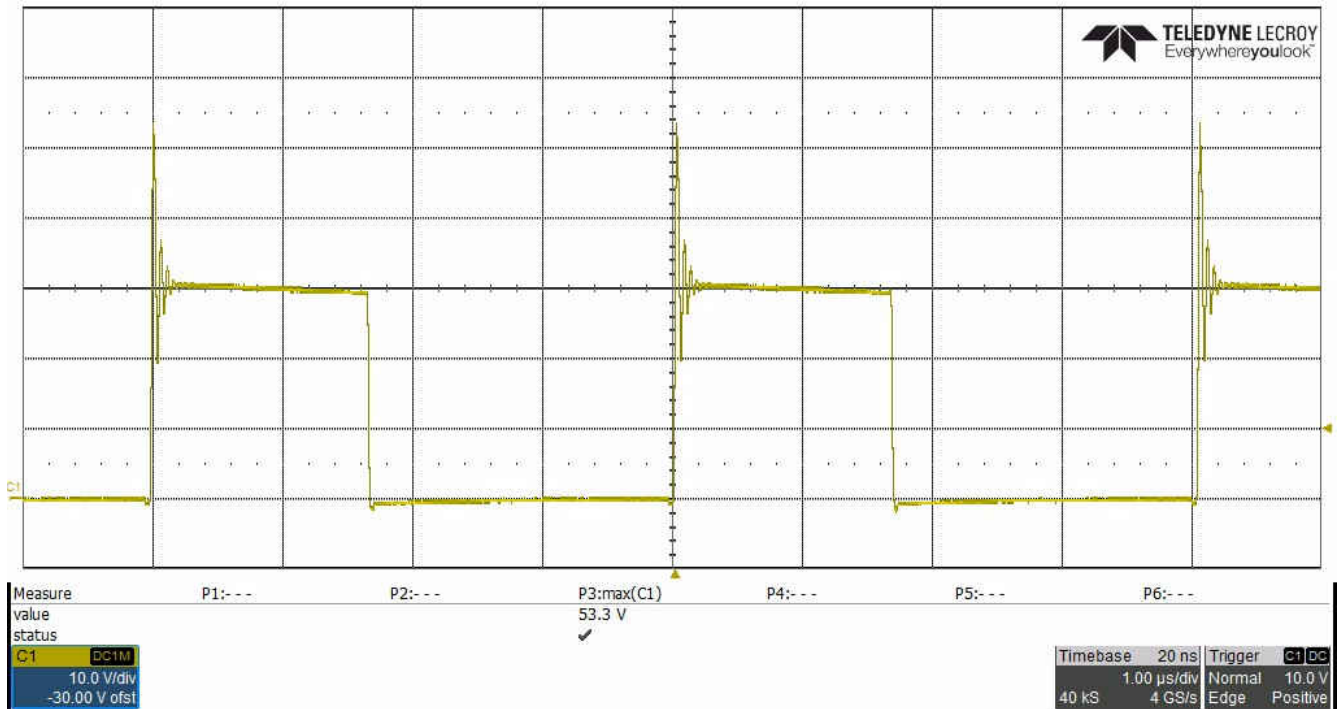
### 3 Waveforms

#### 3.1 Switching

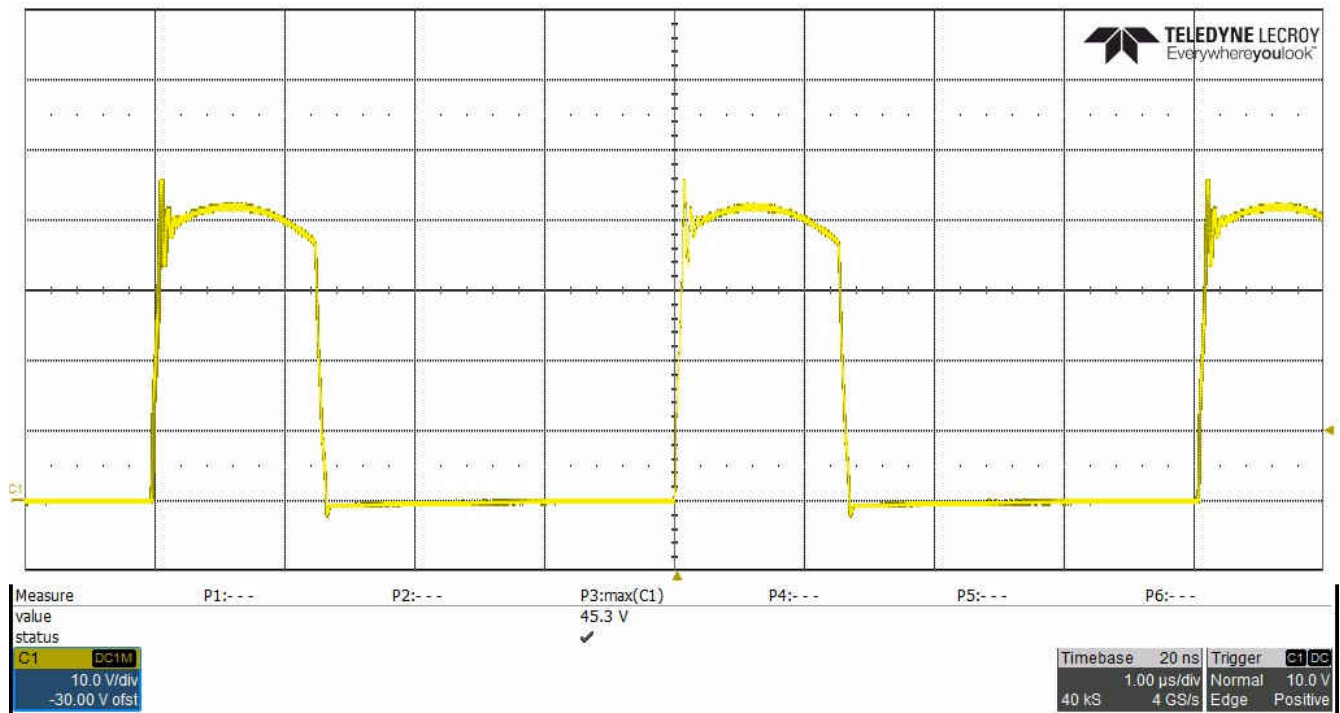
Switching behavior is shown in the following figures.



**Figure 3-1. Voltage Drain-to-Source, Q10, 57-V Input, 2.1-A Load, 20 V/div, 1 µs/div, Measured 105.3 Vpeak**



**Figure 3-2. Voltage Drain-to-Source, Q6, 57-V Input, 2.1-A Load, 10 V/div, 1 µs/div, Measured 53.3 Vpeak**



**Figure 3-3. Voltage Drain-to-Source, Q8, 37-V Input, 2.1-A Load, 10 V/div, 1 μs/div, Measured 45.3 Vpeak**



### 3.2 Voltage Ripple

Ripple measurements taken with a 48-V input, 2.1-A load, and 20-MHz Bandwidth Limit (BWL).

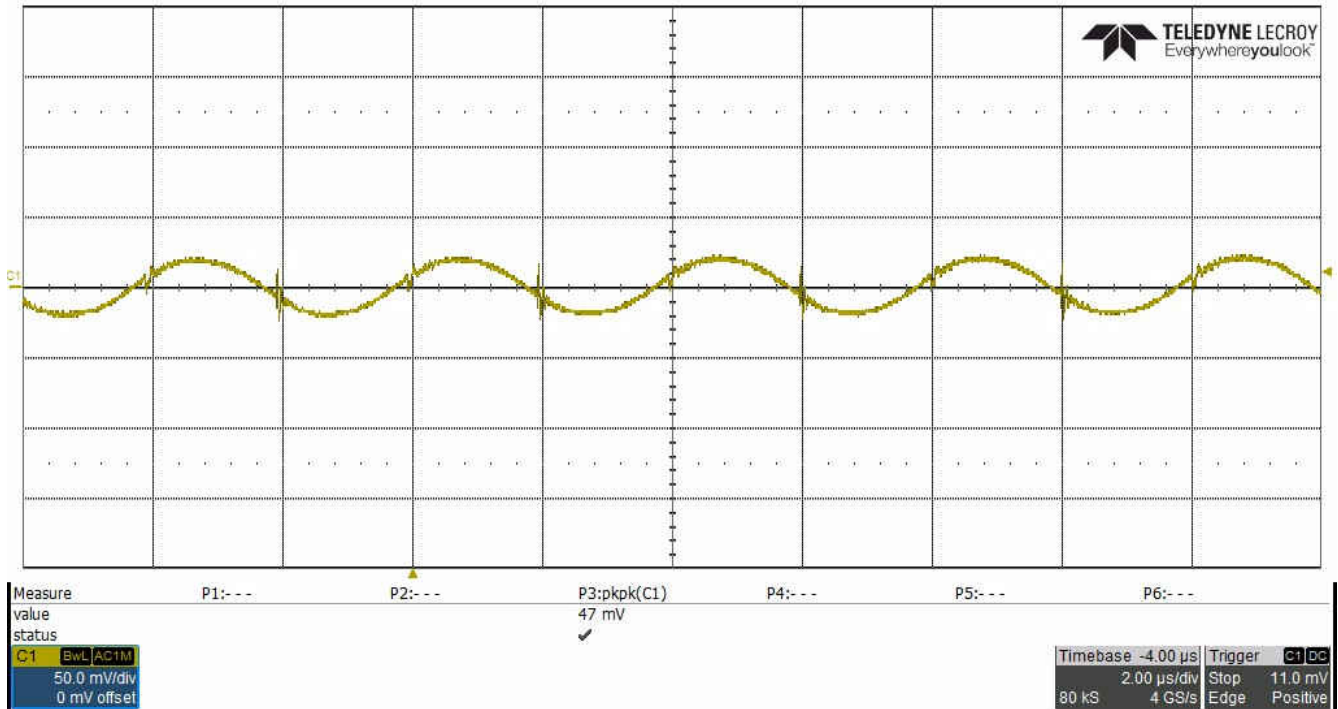


Figure 3-4. Output Ripple (J9), 50 mV/div, 2 μs/div, Measured 47 mVpp

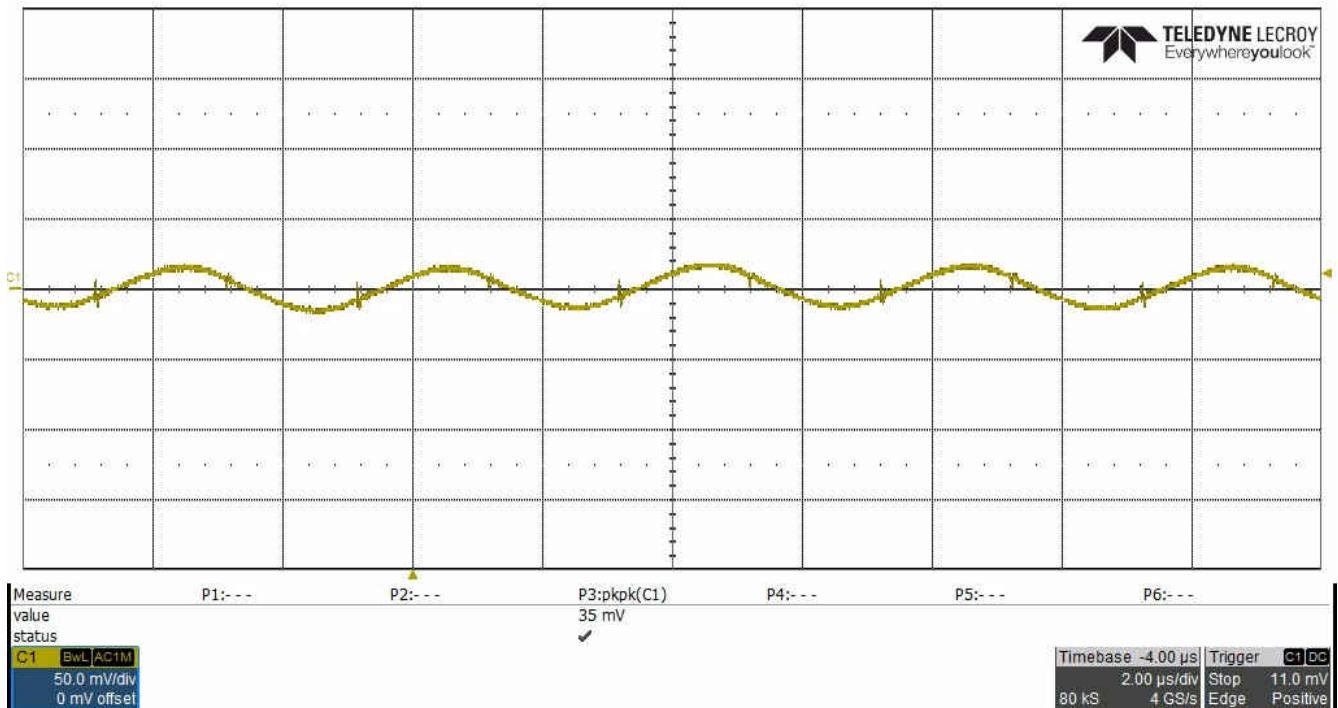


Figure 3-5. Input Ripple (C42), 50 mV/div, 2 μs/div, Measured 35 mVpp

### 3.3 Load Transients

Load transient response is shown in the following figures.

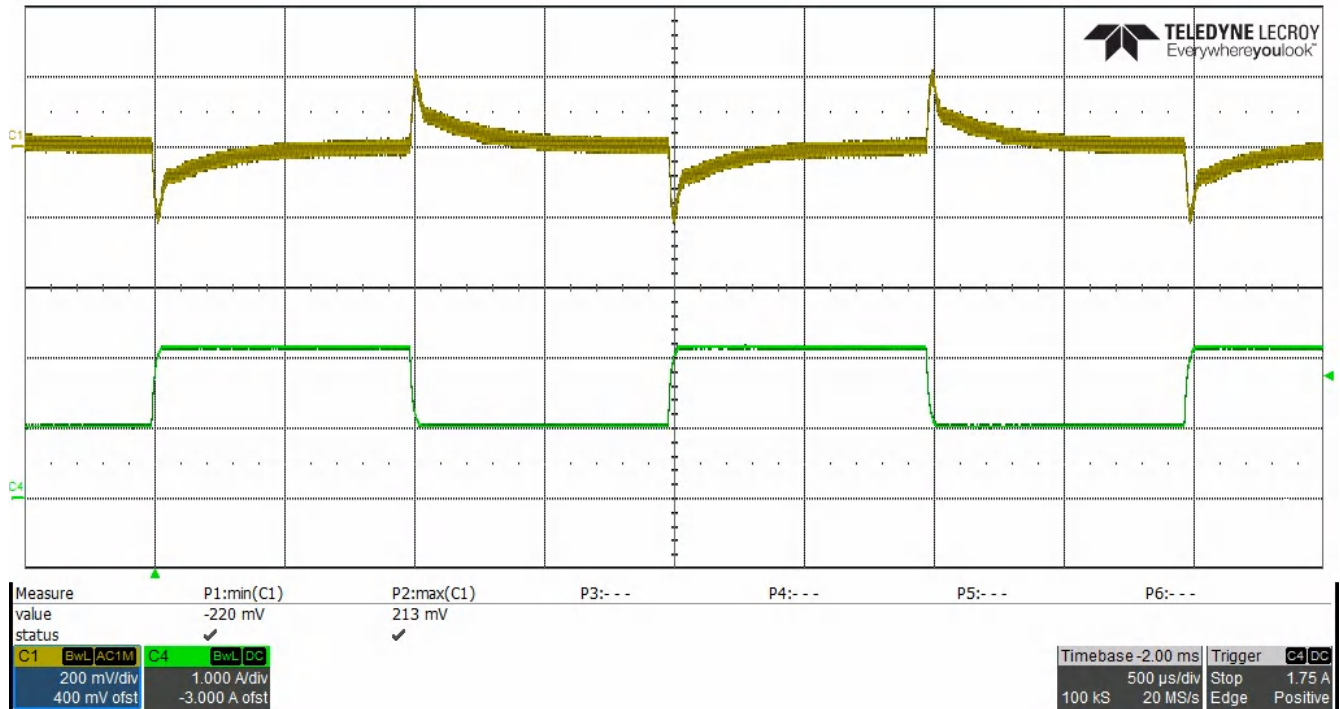


Figure 3-6. Output Load Step Response, 1.00-A to 2.10-A Load Step, 200 mV/div, 1 A/div, 500 µs/div, Slew Rate = 250 mA/µs, Measured -220 mV to +213 mV

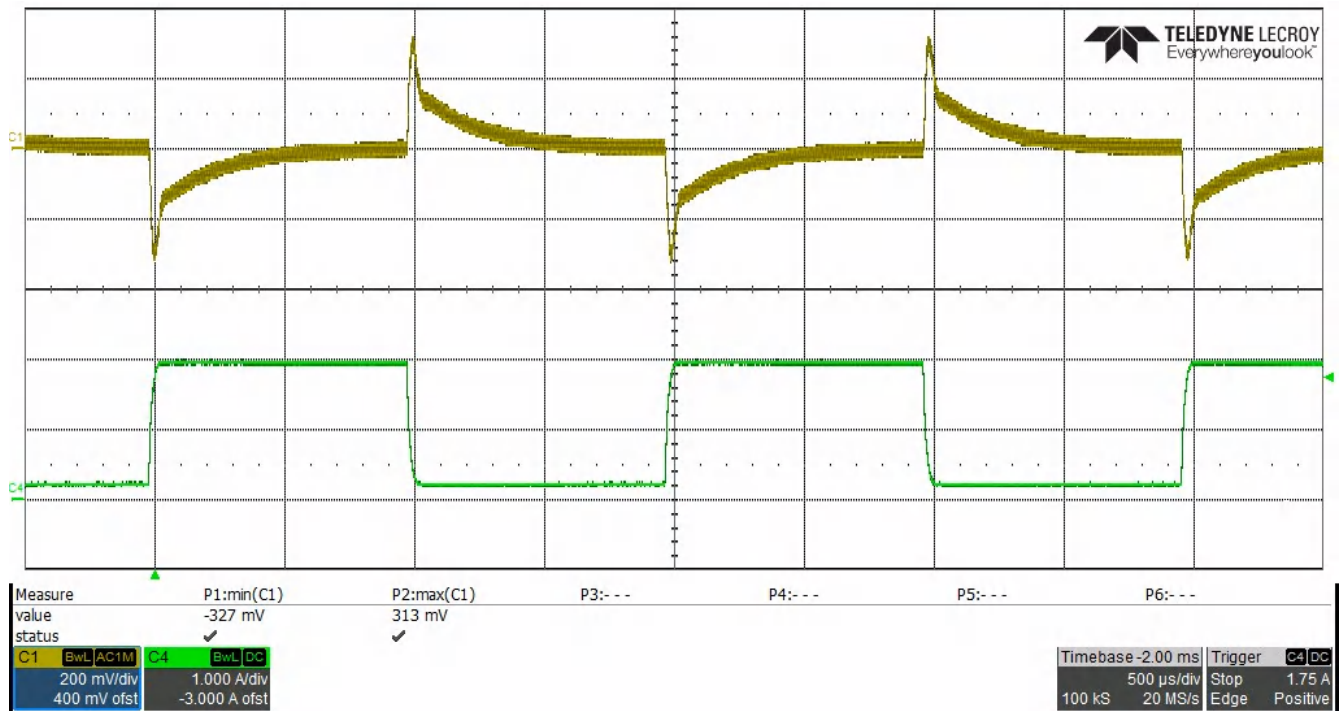


Figure 3-7. Output Load Step Response, 200-mA to 1.90-A Load Step, 200 mV/div, 1 A/div, 500 µs/div, Slew Rate = 250 mA/µs, Measured -327 mV to +313 mV

### 3.4 Short-Circuit Protection

Short at output connector J9. Input power during short circuit is 48.01 V, 150 mA, and 7.20 W.

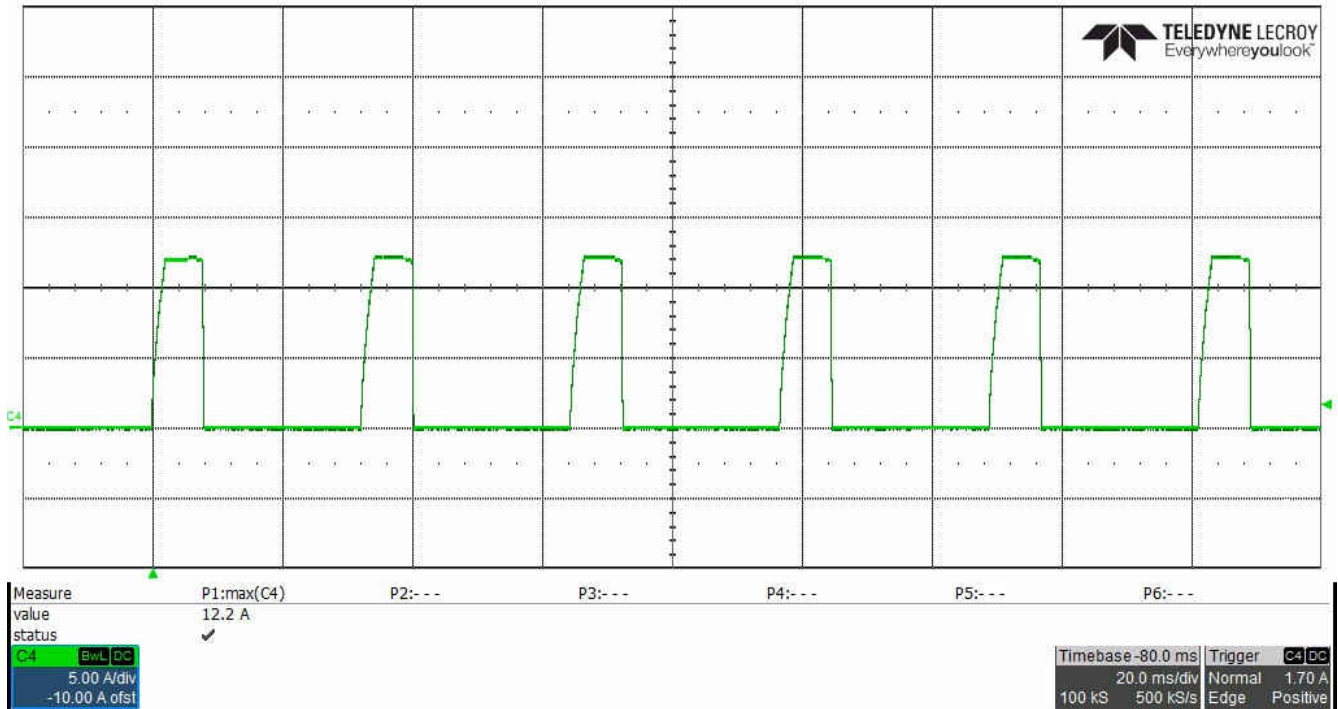


Figure 3-8. Output Current, 5 A/div, 20 ms/div, Measured 12.2 Apeak

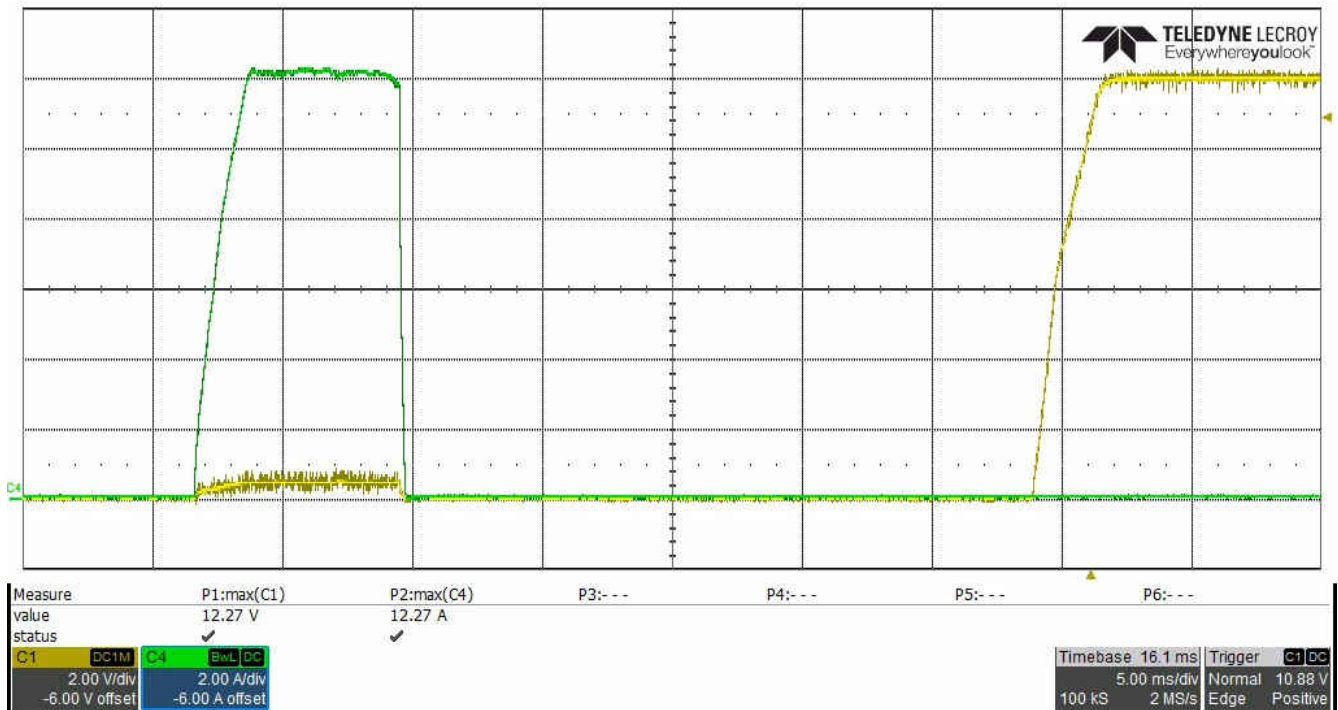


Figure 3-9. Output Voltage Recovery From Short Circuit, 2 V/div, 2 A/div, 5 ms/div

Figure 3-10 and Figure 3-11 show thermal plots during short circuit.

Measurements

Sp1	43.2 °C
Sp2	61.1 °C
Sp3	73.1 °C

Parameters

Emissivity	0.94
Refl. temp.	20 °C

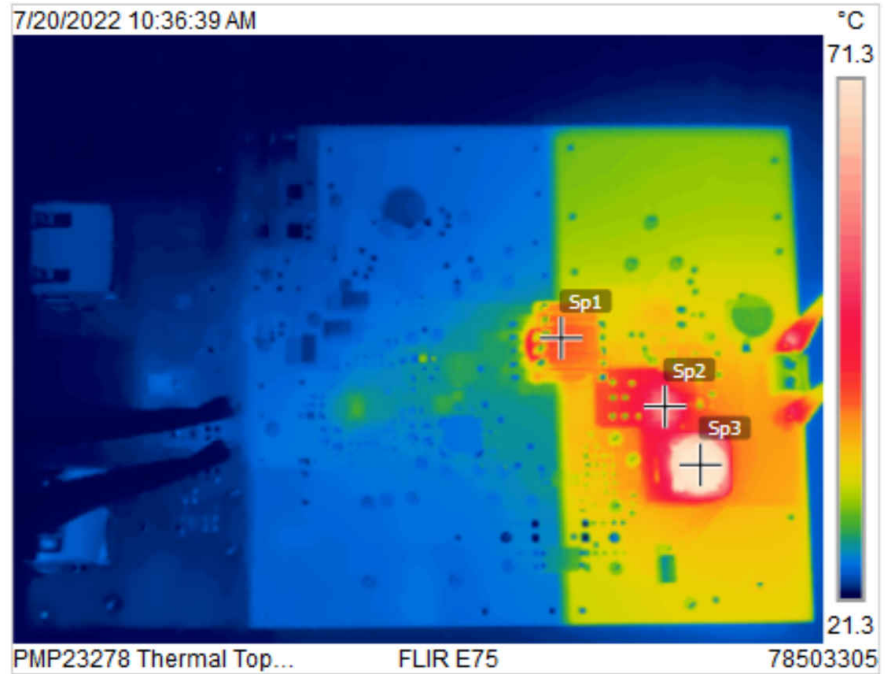


Figure 3-10. Thermal Plot During Short Circuit, Top

Measurements

Sp1	44.4 °C
-----	---------

Parameters

Emissivity	0.94
Refl. temp.	20 °C

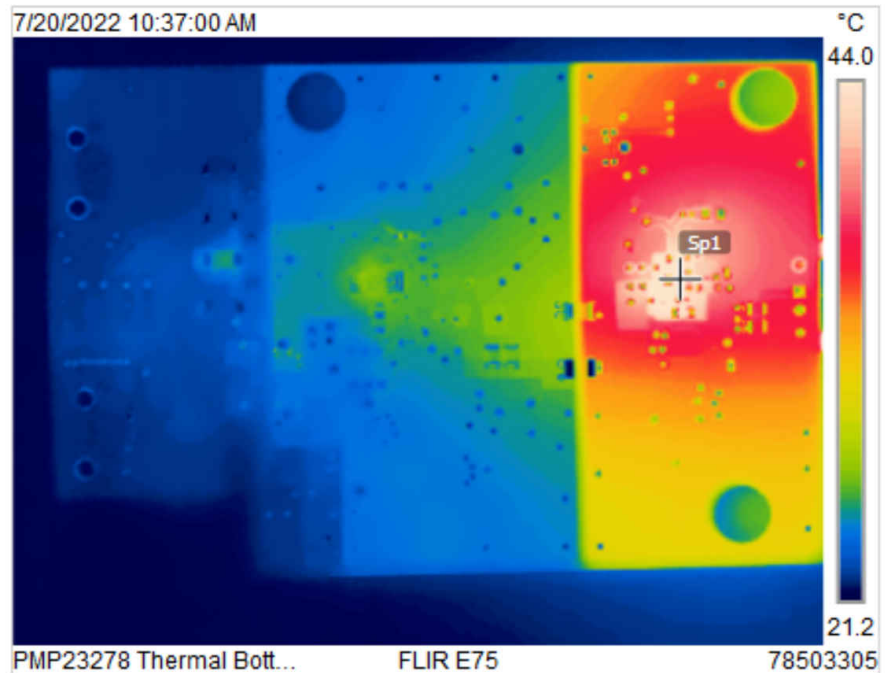


Figure 3-11. Thermal Plot During Short Circuit, Bottom

### 3.5 Start-Up Sequence

Start-up behavior is shown in the following figures.

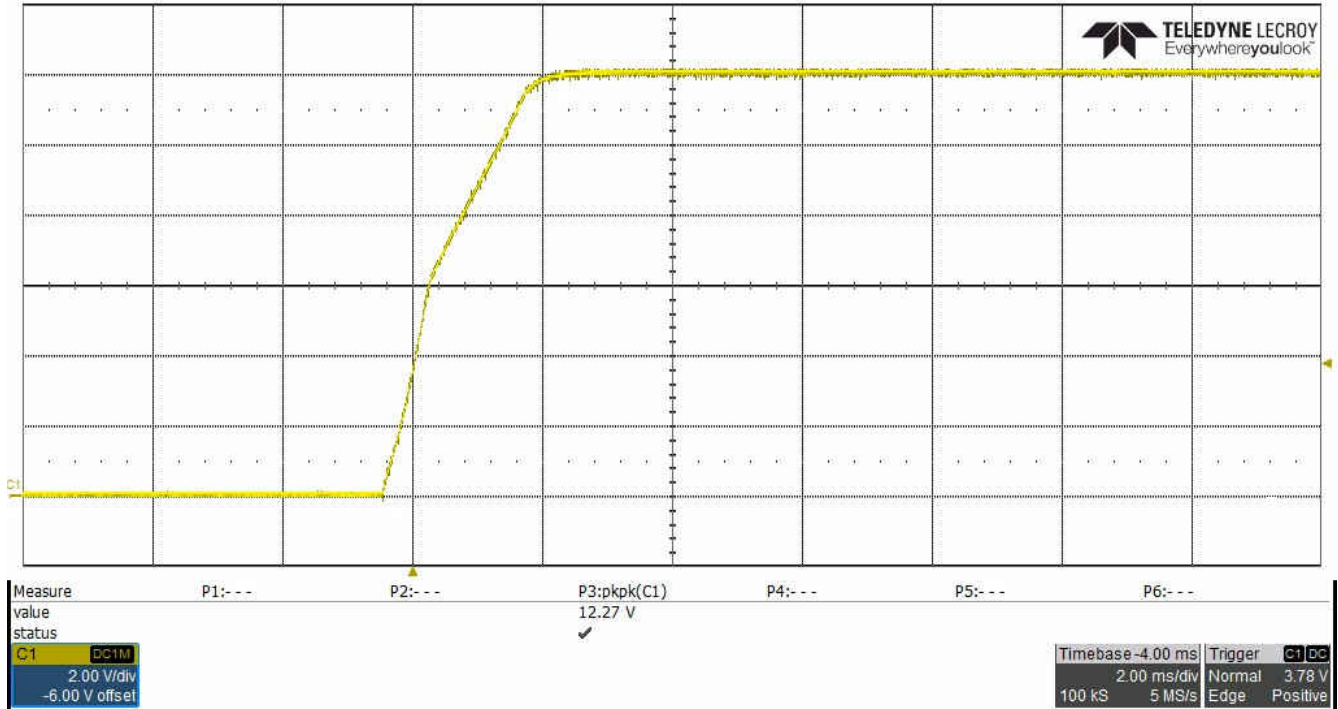


Figure 3-12. 0-A Load, 2 ms/div, 2 V/div

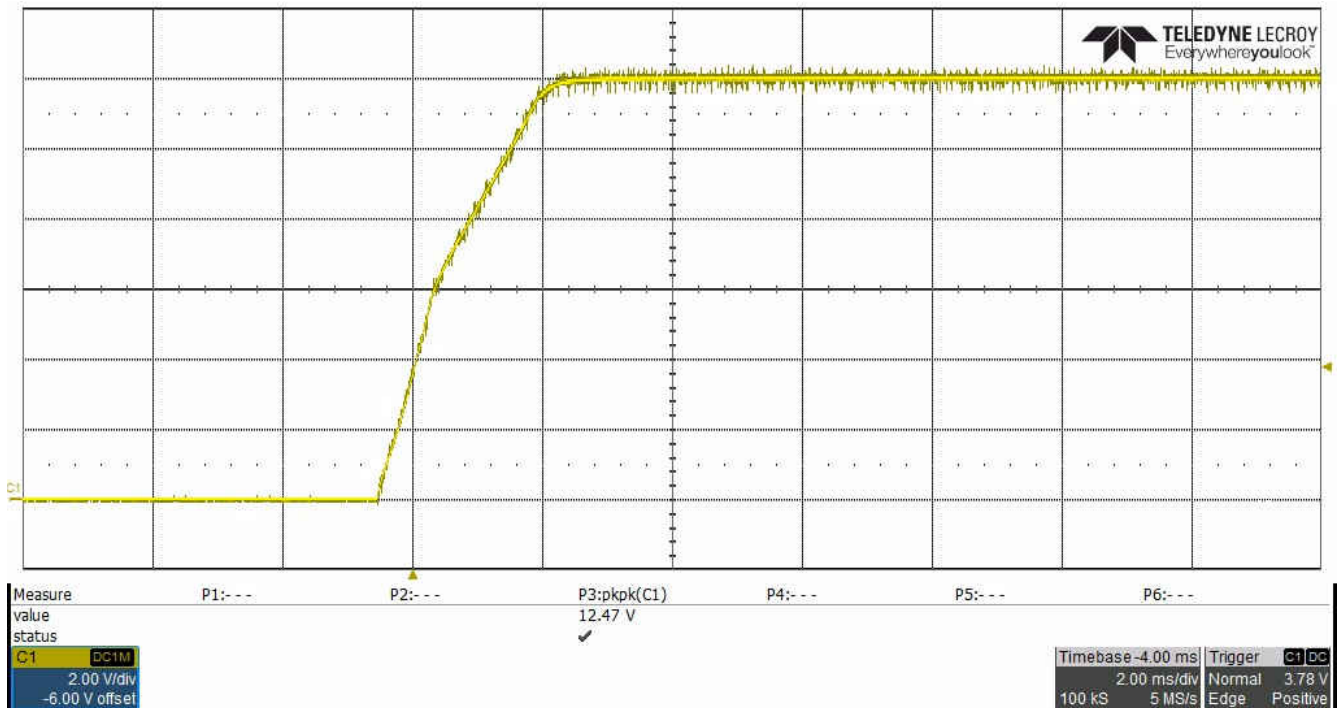


Figure 3-13. 2.1-A Load, 2 ms/div, 2 V/div

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2022, Texas Instruments Incorporated